

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	16	"5294290"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 14:43
S2	1	("5294290").PN.	USPAT; USOCR	OR	OFF	2009/05/01 14:43
S3	1	("6662439").PN.	USPAT; USOCR	OR	OFF	2009/05/01 14:56
S4	87	laser ablation with sacrificial	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:11
S5	13	laser ablation with sacrificial and (PTFE or fluorin\$ or teflon)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:12
S6	62	laser ablation with sacrificial and (PVD or PECVD or deposition or CVD)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:13
S7	7434	laser ablation and @PY< "2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:32
S8	4766	laser ablation and @AY>="2001"<="2002"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:33
S9	3326	laser ablation and @AY>="2000"<="2001"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:33
S10	126	laser ablation and metal with insulator and @AY>="2000"<="2001"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:34
S11	351	laser ablation and metal with layer with insulator and (PECVD or PVD or CVD or vapor deposition)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:36

S12	164	laser ablation and metal with layer with insulator and (PECVD or PVD or CVD or vapor deposition) and (intermediat\$3 or sacrific\$5 or tie)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:37
S13	48	laser ablation and metal with layer with insulator and (PECVD or PVD or CVD or vapor deposition) and (intermediat\$3 or sacrific\$5 or tie) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:37
S14	3	laser ablation and metal with layer with (PVD or physical vapor deposition) with insulator with (PECVD or CVD or plasma or vapor deposition) and (intermediat\$3) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:41
S15	9	laser ablation and metal with layer with (PVD or physical vapor deposition) and insulator with (PECVD or CVD or plasma or vapor deposition) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:41
S16	1152	laser ablation and (conductor or metal) with (dielectric or insulator or "sio.sub.2" or silicon oxide or silicon dioxide) and (PVD or PECVD or CVD or vapor deposition) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:43
S17	1690	204/157.15,157.41,157.61.ccls. or 216/94,95.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:44
S18	3	S16 and S17	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:44
S19	24	laser ablation and (conductor or metal) with (dielectric or insulator or "sio.sub.2" or silicon oxide or silicon dioxide) with (PTFE or polytetrafluoroethylene or fluorin\$5) and (PVD or PECVD or CVD or vapor deposition) and @AY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/01 15:54
S20	2	((("4987006") or ("4752455"))).FN.	USPAT; USOCR	OR	OFF	2009/05/01 16:22
S21	39	("4783695" "4835704" "4894115" "5073814" "5130229" "5173442").FN. OR ("5302547").URFN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/05/01 17:32
S22	646	flexible and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:02

S23	310	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:03
S24	36	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum) and electron beam	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:03
S25	5	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum) and electron beam and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:03
S26	60	flexible with (substrate or circuit) and interconnect and (PVD or physical vapor deposition) with (metal or copper or gold or aluminum) and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/04 13:14
S27	2	"5073814".pn.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/05 16:48
S28	36	"5302547"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:34
S29	309	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:37
S30	63	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:38
S31	8	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric and @PY< "2004" and plasma with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:38
S32	63	(interconnect or via) and sensor and flexible with polymer with substrate and polymer with dielectric and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:44
S34	5	(interconnect or via) and flexible with polymer with substrate and polymer with dielectric and @PY< "2004" and plasma with adhesion not S31	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 15:49

S35	849	@PY< "2004" and plasma with adhesion and interconnect\$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
S36	4	@PY< "2004" and polymer with metal with plasma with adhesion and interconnect\$3 with device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
S37	92	@PY< "2004" and polymer with metal with plasma with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
S38	0	@PY< "2004" and polymer with metal with plasma with adhesion with device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
S39	48	@PY< "2004" and polymer with metal with plasma with adhesion and device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:18
S40	19	@PY< "2004" and polymer with metal with plasma with adhesion and (electrical or electronic or semiconductor) with device	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:19
S41	2	((("4,765,860") or ("4,382,101"))).PN.	USPAT; USOCR	OR	OFF	2009/05/06 16:24
S42	490	SN with hard mask and mask with thickness	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:39
S43	113	SN with hard mask and mask with thickness and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:39
S44	0	SN with hard mask and mask with thickness with suitable and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:40
S45	1	SN with hard mask and mask with thickness with variable and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41
S46	0	SN with hard mask and mask with thickness with designand @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41

S47	0	SIN with hard mask and mask with thickness with design and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41
S48	10	SIN with hard mask and mask with thickness with effect\$8 and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:41
S49	10	SIN with hard mask and mask with thickness with etch and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:43
S50	48	hard mask and mask with thickness with effect\$8 and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:46
S51	16	hard mask and mask with thickness with varied and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 16:48
S52	13	(interconnect or via) and flexible with polymer with substrate and polymer with dielectric and @PY< "2004" and plasma with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:07
S53	19	(interconnect or via) and solar cell and flexible with polymer with substrate and polymer with dielectric and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:19
S54	12	(interconnect) and solar cell and flexible with polymer with substrate and polymer with dielectric and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:23
S55	16	(interconnect or via) with flexible with polymer with substrate and polymer with dielectric and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:28
S56	0	(interconnect or via) with flexible with substrate with solar cell and polymer with dielectric and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:34
S57	11	(interconnect or via) with flexible with substrate with solar cell and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:34

S58	50	(interconnect or via) with flexible with polymer with polyimide	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:55
S59	24	(interconnect or via) with flexible with polymer with polyimide and (sputter \$3 or PVD or evaporat\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 12:55
S60	0	(interconnect) with flexible with polymer with polyimide and (sputter \$3 or PVD or evaporat\$3) with (pad)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 13:03
S61	3	sputter with chip pad	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 13:06
S62	39	sputter\$3 with chip pad	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 13:07
S63	31813	sputter\$3 with aluminum	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 13:10
S64	708	sputter\$3 with aluminum with pad	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 13:10
S65	245	sputter\$3 with aluminum with pad and @PY< "2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 13:10
S66	66	sputter\$3 with aluminum with pad and @PY< "2003" and interconnect	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 13:10
S67	2	"US 20070264421"	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2009/11/15 13:57
S68	3	MgO with mask with laser	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/15 14:20

S70	2	(magnesia or magnesium oxide or MgO) with (alumina or aluminum oxide or Al2O3 or "al.sub.2" "O. sub.3") with (PECVD or plasma) and 427/248.1.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/15 15:39
S71	286	(magnesia or magnesium oxide or MgO) with (alumina or aluminum oxide or Al2O3 or "al.sub.2" "O. sub.3") with (PECVD or plasma) and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/15 15:39
S72	258	(magnesia or magnesium oxide or MgO) with (alumina or aluminum oxide or Al2O3 or "al.sub.2" "O. sub.3") with (PECVD or plasma) and @PY< "2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/15 15:40
S73	25	(magnesia or magnesium oxide or MgO) with (alumina or aluminum oxide or Al2O3 or "al.sub.2" "O. sub.3") with (PECVD or plasma) and @PY< "2003" and "427".clas.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/15 15:40
S74	3	(magnesia or magnesium oxide or MgO) with (alumina or aluminum oxide or Al2O3 or "al.sub.2" "O. sub.3") with (PECVD or plasma with (vapor deposition or CVD)) and @PY< "2003" and "427".clas.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/15 15:44
S75	1639	427/534,552,555.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 09:41
S76	1841	204/157.15,157.41,157.61.ccls. or 216/94,95.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 10:24
S77	2175	204/192.32-192.37.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 10:27
S79	217	204/298.36.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 10:28
S80	98909	(selective or differential) near5 (etch \$3 or sputter\$3 or ablat\$3 or heat\$3 or evaporat\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 10:29
S81	23	S80 and S79	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 10:30

S82	4973	(selective or differential) near5 (etch \$3 or sputter\$3 or ablat\$3 or heat\$3 or evaporat\$3) AND sacrificial layer	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 11:11
S83	1297	(selective or differential) near5 (etch \$3 or sputter\$3 or ablat\$3 or heat\$3 or evaporat\$3) AND sacrificial and (teflon or PTFE or fluoropolymer or polytetrafluoroethylene)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 11:12
S84	19	S82 and (S75 or S76 or S77 or S79)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 11:13
S85	4843	(etch\$3 or sputter\$3 or ablat\$3 or heat\$3 or evaporat\$3) AND sacrificial and (teflon or PTFE or fluoropolymer or polytetrafluoroethylene)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 11:19
S86	32	S85 and (S75 or S76 or S77 or S79)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 11:19
S87	35	("3319317" "3953566" "3999004" "4482516" "4705762" "4985296" "5316803" "5593606").PN. OR ("5731047").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/09/24 11:39
S88	12	("3319317" "3953566" "3999004" "4482516" "4705762" "4985296" "5316803" "5593606").PN. OR ("5731047").URPN. and S85	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/09/24 11:42
S89	123	("3562009" "3931458" "4761786" "4832788" "4894115" "4915981" "5063280" "5073687" "5087396" "5108785" "5153408" "5168454" "5194713" "5293025" "5378869" "5453315").PN. OR ("5593606").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/09/24 12:02
S90	28	("3562009" "3931458" "4761786" "4832788" "4894115" "4915981" "5063280" "5073687" "5087396" "5108785" "5153408" "5168454" "5194713" "5293025" "5378869" "5453315").PN. OR ("5593606").URPN. and S85	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/09/24 12:03
S91	1011	427/552,555.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 12:28
S92	26	427/552,555.ccls. and sacrificial	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 12:29

S93	2	"20040017428".pn.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/09/24 12:37
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EAST Search History (Interference)

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